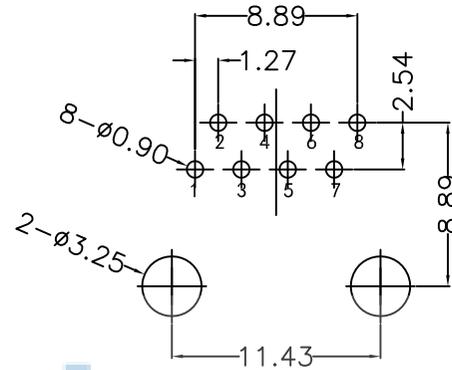
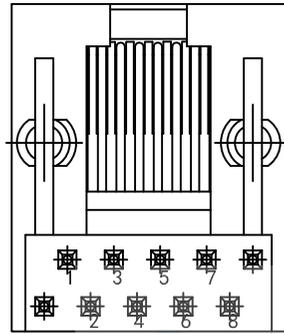
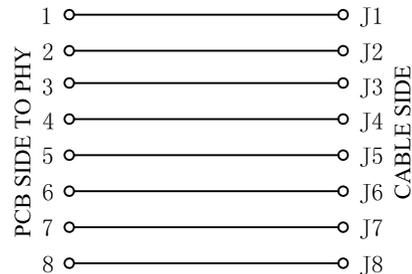
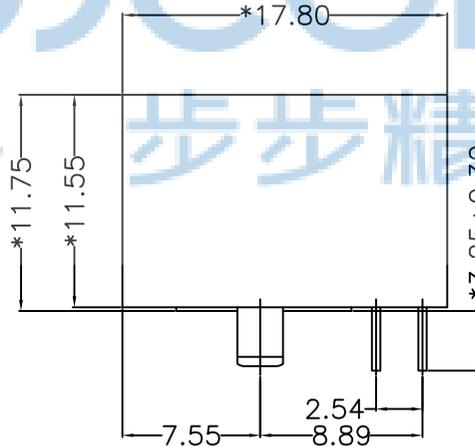
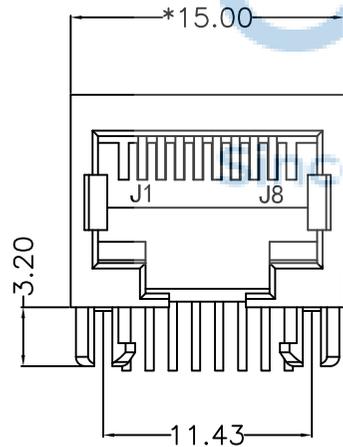


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



RECOMMENDED PCB LAYOUT
VIEWED FROM COMPONENT SIDE



MATERIAL:
HOUSING: PBT,UL94V-0,BLACK.
TERMINAL: PHOSPHOR BRONZE Ø=0.46MM, G/FU" GOLD PLATING.

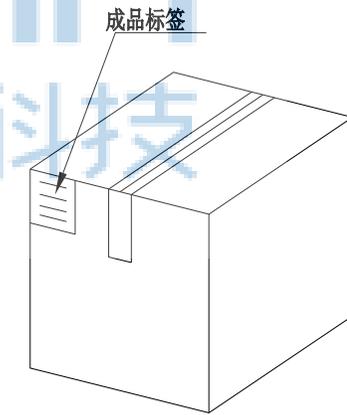
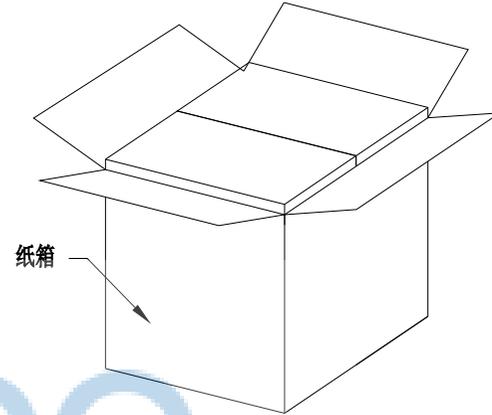
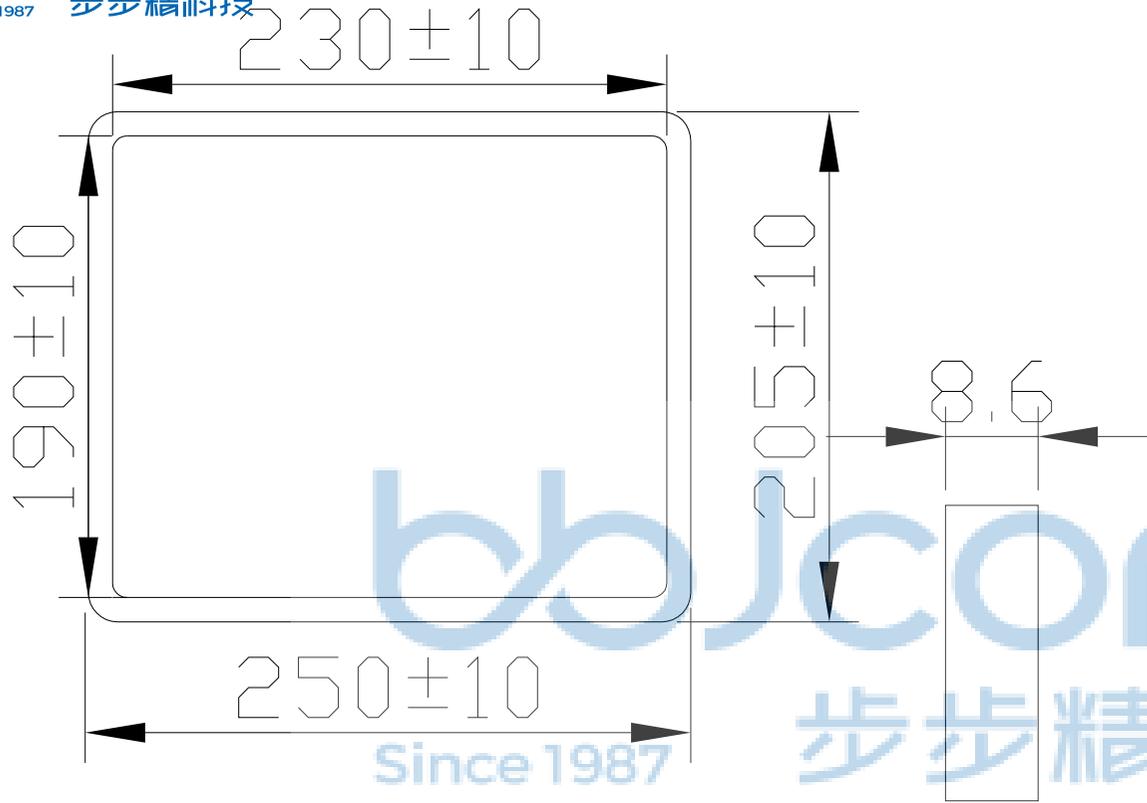
MACHANICAL:
DURABILITY: 750 CYCLES MIN,12.5MM/MINUTE.
INSERTION FORCE: 2.2KG.F MAX.
RETENTION STRENGTH : 7.7KG.F BETWEEN JACK AND PLUG.
OPERATING TEMPERATURE: -40°C~+85°C.
STORAGE TEMPERATURE: -40°C~+85°C.
ALL CRITICAL DIMENSIONS WITH "※"

ELECTRICAL:
VOLTAGE: 125 VOLTS AC.
CURRENT RATING : 1.5AMP.
DIELECTRIC STRENGTH: 1000 VAC RMS 50HZ OR 60HZ,1MIN.
INSULATION RESISTANCE: 500 MEGA OHMS MIN. INITIAL
AFTER 500V DC FOR 1 MINUTE.
CONTACT RESISTANCE: SINGLE TERMINAL 30 MILLIOHMS MAX.
INITIAL 50 MILLIOHMS MAX. AFTER
DURABILITY TEST.



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			APPD. JM_Zheng		PJ. NO.: RJ.01.12-11-A004
	CHKD. LYX		SIZE: A4 DRW NO.:		
	DR. SGF		FINISH: SEE NOTES MAT'L.: SEE NOTES		
		SCALE: N/A	REV.: A0	UNIT: mm	PAGE: 1/2

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



纸箱规格: 350*210*290

1. 包装要求:
- 1.1 每盒吸塑盒包装100 pcs;
 - 1.2 每40盘放一箱, 共计4000PCS;
 - 1.3 纸箱外贴上标签

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APPD.	JM_Zheng	PJ. NO.: RJ.01.12-11-A004		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG.NO:	0521-1	DR.	SGF	SCALE: N/A	REV.: A0
				UNIT: mm	PAGE: 2/2